

30V P-Channel Enhancement Mode MOSFET

Description

The CP35QP03 uses advanced trench technology to provide excellent $R_{DS(ON)}$. This device is suitable for use as a load switch or in PWM applications.

General Features

- ◆ $V_{DS} = -30V$ $I_D = -35A$
 $R_{DS(ON)}(Typ.) = 11.8m\Omega$ @ $V_{GS} = -10V$
 $R_{DS(ON)}(Typ.) = 17.2m\Omega$ @ $V_{GS} = -4.5V$
- ◆ High power and current handling capability
- ◆ Lead free product is acquired
- ◆ Surface mount package
- ◆ 150 °C operating temperature
- ◆ 100% UIS tested

Application

- ◆ PWM applications
- ◆ Load switch
- ◆ Uninterruptible power supply

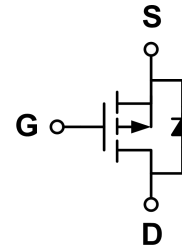
Package

- ◆ PDFN3*3-8L

100% UIS TESTED!

100% ΔV_{ds} TESTED!

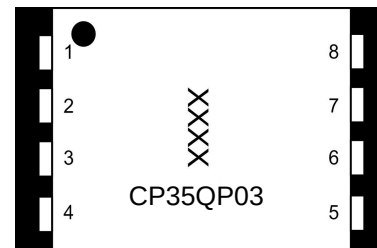
Schematic diagram



Marking and pin assignment

PDFN3 3-8L

(Top View)



Ordering Information

Part Number	Storage Temperature	Package	Devices Per Reel
CP35QP03	-55°C to +150°C	PDFN3*3-8L	5000

Absolute Maximum Ratings (TA=25 unless otherwise noted)

parameter		symbol	limit	unit
Drain-source voltage		V_{DS}	-30	V
Gate-source voltage		V_{GS}	±25	V
Continuous Drain Current	TC=25°C	I_D	-35	A
	TC=70°C		-23	
Pulsed Drain Current		I_{DP}	-120	A
Avalanche energy($T_J=25^\circ C$, $V_{DD}=30V$, $V_G=10V$, $L=0.5mH$, $R_g=25\Omega$)		E_{AS}	45	mJ
Power Dissipation	TC=25°C	P_D	29	W
	TC=70°C		12	
Operating junction Temperature range		T_J	-55—150	°C

Electrical Characteristics (TA=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	BV _{DSS}	V _{GS} =0V, I _D =-250μA	-30	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =-30V, V _{GS} =0V	-	-	-1	μA
		T _J =55°C	-	-	-5	
Gate Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±25V	-	-	±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =-250μA	-1.7	-2.2	-3	V
Drain-source on-state resistance ¹	R _{DS(ON)}	V _{GS} =-10V, I _D =-10A	-	11.8	14	mΩ
		V _{GS} =-4.5V, I _D =-10A	-	17.8	20	
On Status Drain Current	I _{D(ON)}	V _{DS} =-5V, V _{GS} =-10V	-100	-	-	A
Diode Characteristics						
Diode Forward Voltage ¹	V _{SD}	I _{SD} =-20A, V _{GS} =0V	-	-0.8	-1.3	V
Diode Continuous Forward Current	I _S		-	-30	-	A
Reverse Recovery Time	t _{rr}	I _F =-30A, dI/dt=-100A/us	-	24	-	ns
Reverse Recovery Charge	Q _{rr}		-	16	-	nC
Dynamic Characteristics²						
Gate Resistance	R _G	V _{GS} =0V, V _{DS} =0V, f=1MHz	-	2.4	-	Ω
Input capacitance	C _{ISS}	V _{GS} =0V, V _{DS} =-15V f=1.0MHz	-	2150	-	pF
Output capacitance	C _{OSS}		-	307	-	
Reverse transfer capacitance	C _{RSS}		-	269	-	
Turn-on delay time	t _{D(ON)}	V _{GS} =-10V, V _{DS} =-15V, R _L =1.6Ω, I _D =30A, R _G =3Ω	-	11	-	ns
Turn-on Rise time	t _r		-	9.4	-	
Turn-off delay time	t _{D(OFF)}		-	24	-	
Turn-off Fall time	t _f		-	12	-	
Total gate charge	Q _g	V _{GS} =-10V, I _D =-10A V _{DS} =-15V	-	44.3	-	nC
Gate-source charge	Q _{gs}		-	5.3	-	
Gate-drain charge	Q _{gd}		-	9.6	-	

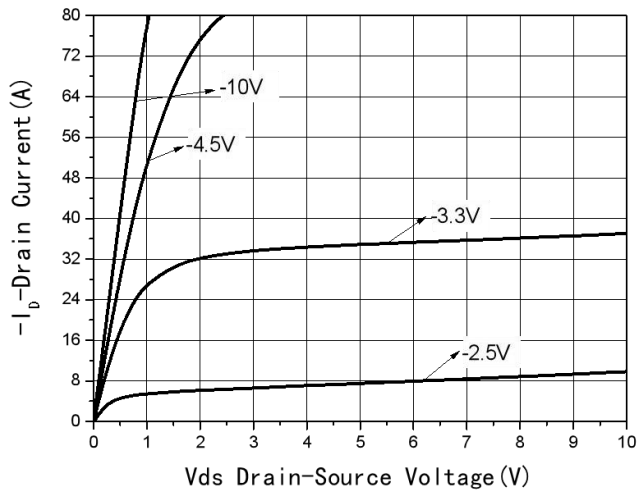
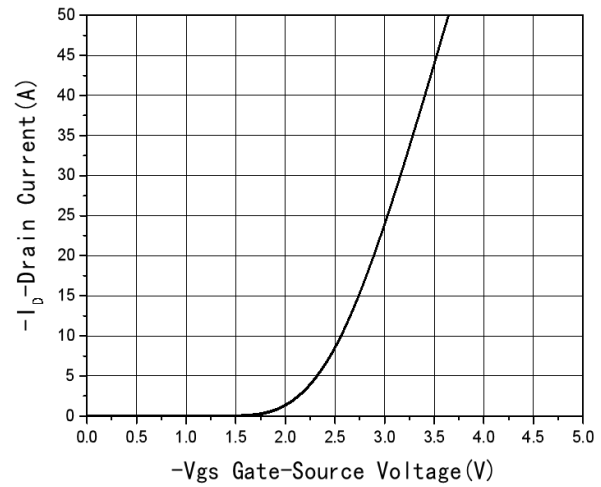
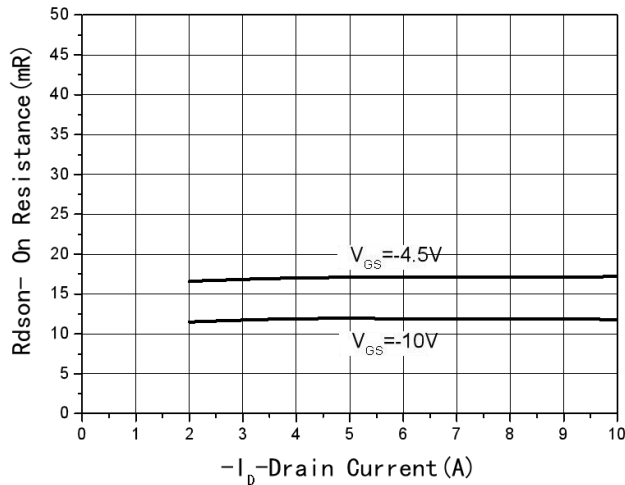
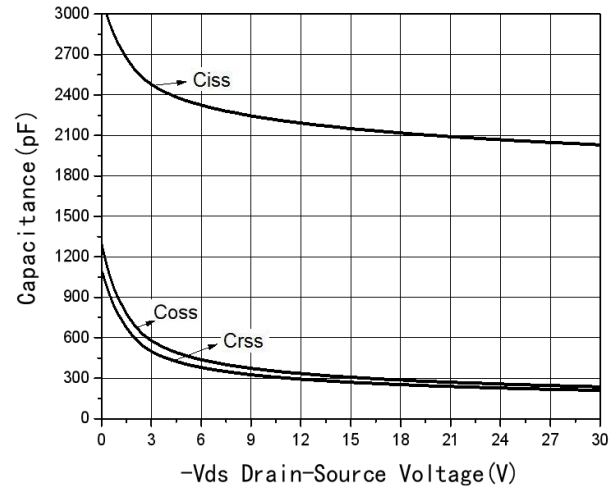
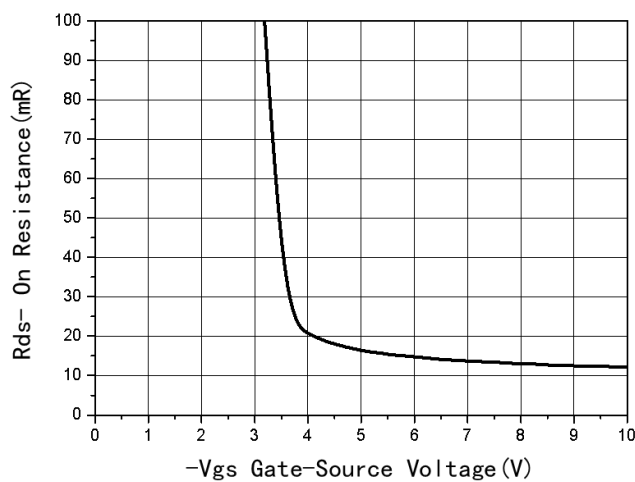
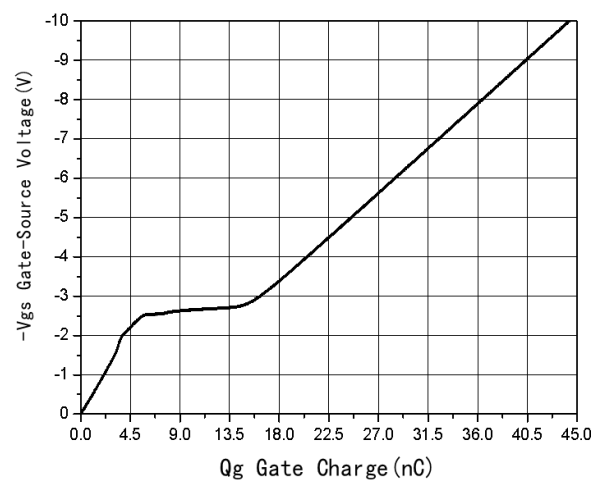
Thermal Characteristics

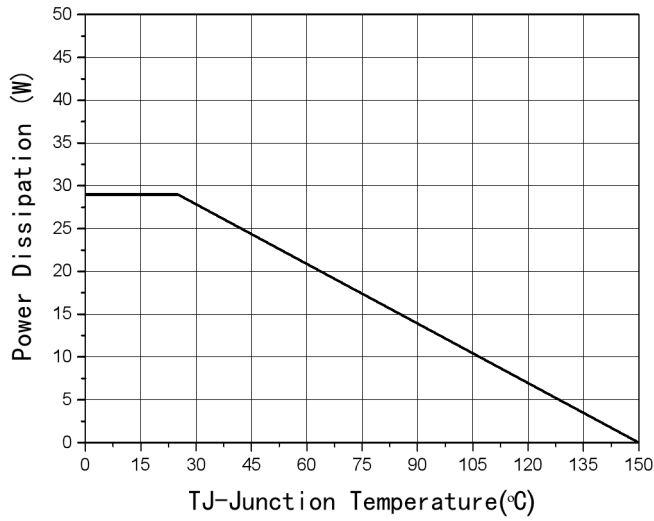
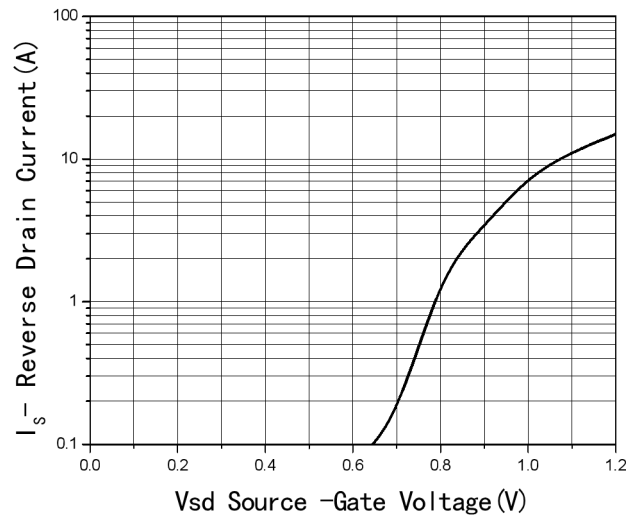
Parameter	Symbol	Typ	Max	Unit
Maximum Junction-to-Ambient ^A	≤ 10s	R _{θJA}	29	°C/W
Maximum Junction-to-Ambient ^A	Steady-State		56	
Maximum Junction-to-Lead ^B	Steady-State	R _{θJC}	3.5	

A: The value of R_{θJA} is measured with the device mounted on 1in 2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The value in any given application depends on the user's specific board design. The current rating is based on the t ≤ 10s thermal resistance rating.

B: The R_{θJA} is the sum of the thermal impedance from junction to lead R_{θJL} and lead to ambient.

Typical Performance Characteristics


Fig1 Output Characteristics

Fig2 Transfer Characteristics

Fig3 $R_{DS(on)}$ -Drain current

Fig4 Capacitance vs V_{DS}

Fig5 $R_{DS(on)}$ -Gate Drain voltage

Fig6 Gate Charge


Fig7 Power De-rating

Fig8 Source-Drain Diode Forward

Package Information

- PDFN3*3-8L